

68V N-Channel Trench MOSFET

Features

- Trench Power Technology
- Low R_{DS(ON)}
- Low Gate Charge
- Optimized for Fast-switching Applications

Applications

- Synchronous Rectification in DC/DC and AC/DC Converters
- Isolated DC/DC Converters in Telecom and Industrial

Product Summary

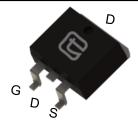
 V_{DS} 68V

 $R_{DS(ON)}$ (at V_{GS} =10V) < 5.0m Ω

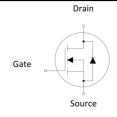
 I_D (at V_{GS} =10V) 135A

100% UIS Tested









Device	Package	Marking
TTB135N68A	TO-263	135N68A
TTP135N68A	TO-220	135N68A

Absolute Maximum Ratings $T_C = 25^{\circ}C$, unless otherwise noted				
Parameter		Symbol	Value	Unit
Drain-Source Voltage (V _{GS} = 0V)		V _{DSS}	68	V
Continuous Danie Comment	$T_{\rm C} = 25^{\rm o}{\rm C}$		135	А
Continuous Drain Current	$T_{\rm C} = 100^{\rm o}{\rm C}$	l _D	94	
Pulsed Drain Current (note1)) I _{DM}	540	Α
Gate-Source Voltage		V_{GSS}	±20	V
Single Pulse Avalanche Energy (note2)) E _{AS}	290	mJ
Avalanche Current		I _{As}	44	Α
Power Dissipation (note3)	$T_{\rm C} = 25^{\circ}{\rm C}$		160	W
	$T_{\rm C} = 100^{\circ}{\rm C}$	P _D	80	W
Operating Junction and Storage Temperature Range		T _J , T _{stg}	-55~+175	∘C

Thermal Resistance			
Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case	R_{thJC}	0.95	00/1/
Thermal Resistance, Junction-to-Ambient	R _{thJA}	65	°C/W



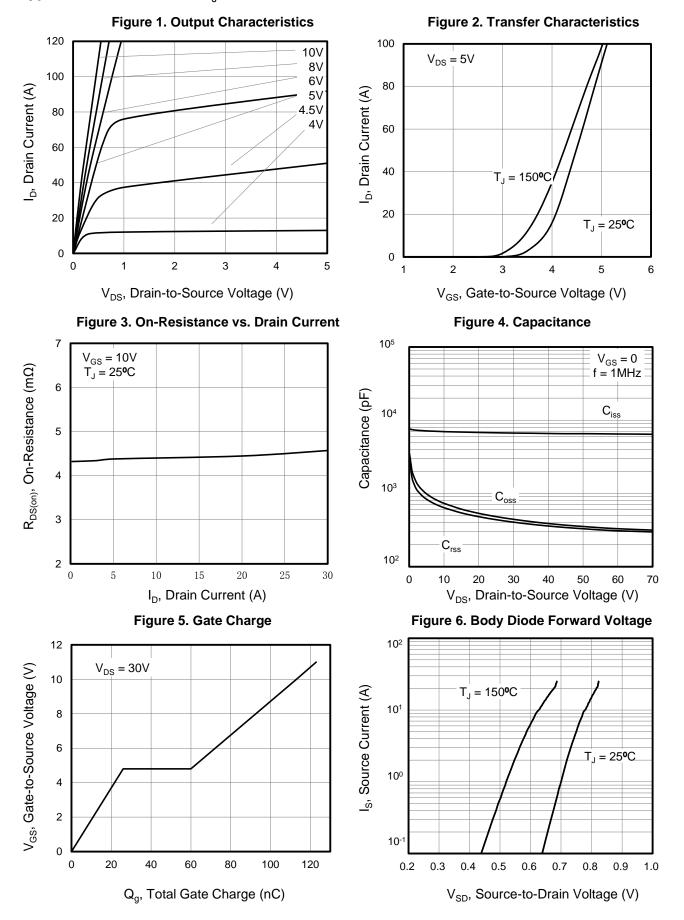
Specifications $T_J = 25^{\circ}C$, unless otherwise noted						
Parameter	0h.a.l	T . O . III	Value			11.24
	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Static						
Drain-Source Breakdown Voltage	V _{(BR)DSS}	$V_{GS} = 0V, I_{D} = 250\mu A$	68			V
Zoro Coto Voltago Drain Current		$V_{DS} = 68V, V_{GS} = 0V, T_{J} = 25^{\circ}C$			1	μА
Zero Gate Voltage Drain Current	I _{DSS}	$V_{DS} = 68V, V_{GS} = 0V, T_{J} = 100^{\circ}C$			25	
Gate-Source Leakage	I _{GSS}	$V_{GS} = \pm 20V$			±100	nA
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	2	3	4	V
Drain-Source On-Resistance	R _{DS(on)}	V _{GS} = 10V, I _D = 30A		4.2	5.0	mΩ
Forward Transconductance	g _{fs}	$V_{DS} = 5V, I_{D} = 20A$	30			S
Dynamic						
Input Capacitance	C _{iss}	V = 0V		6646		
Output Capacitance	C _{oss}	$V_{GS} = 0V,$ $V_{DS} = 30V,$		443		pF
Reverse Transfer Capacitance	C _{rss}	f = 1.0MHz		396		
Total Gate Charge	Q_g			114		
Gate-Source Charge	Q_{gs}	$V_{DD} = 30V, I_{D} = 30A, V_{GS} = 10V$		26		nC
Gate-Drain Charge	Q_{gd}	- 63		34		
Turn-on Delay Time	t _{d(on)}			17		
Turn-on Rise Time	t _r	$V_{DD} = 30V, I_{D} = 30A,$		11		
Turn-off Delay Time	t _{d(off)}	$R_G = 2.5\Omega$		55		ns
Turn-off Fall Time	t _f			15		
Drain-Source Body Diode Characteristics						
Continuous Body Diode Current	Is	T _C = 25°C			135	Δ
Pulsed Diode Forward Current	I _{SM}				540	Α
Body Diode Voltage	V _{SD}	$T_J = 25^{\circ}C$, $I_{SD} = 20A$, $V_{GS} = 0V$			1.2	V
Reverse Recovery Time	t _{rr}	I _F = 20A, di _F /dt = 100A/μs		30		ns
Reverse Recovery Charge	Q _{rr}			51		nC

Notes

- 1. Repetitive Rating: Pulse Width limited by maximum junction temperature
- 2. $I_{AS} = 44A$, $V_{DD} = 50V$, L=0.3mH, $R_{G} = 25\Omega$, Starting $T_{J} = 25$ °C
- 3. The power dissipation PD is based on $TJ(MAX)=175^{\circ}$ C, using junction-to-case thermal resistance.



Typical Characteristics $T_J = 25^{\circ}\text{C}$, unless otherwise noted





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Figure 7 On Booistones vs Tommoreture

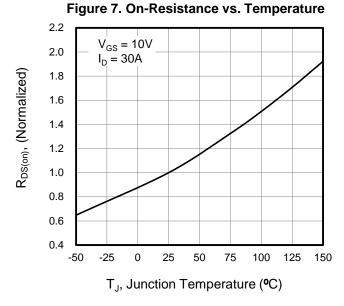
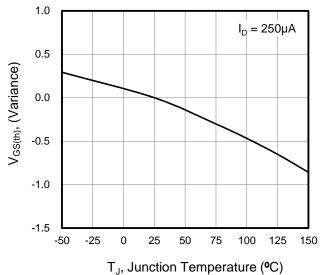


Figure 8. Threshold Voltage vs. Temperature



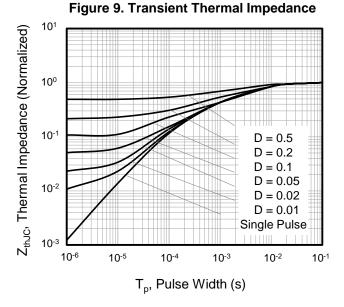


Figure 10. Safe operation area

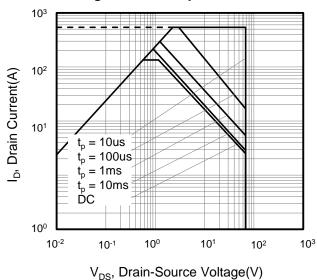




Figure A: Gate Charge Test Circuit and Waveform

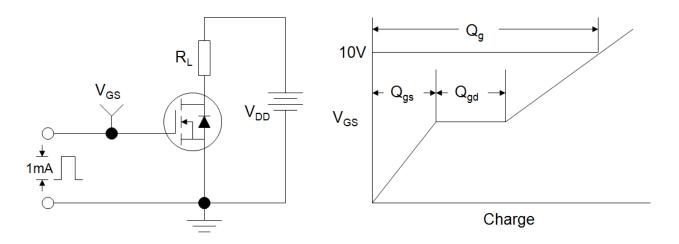


Figure B: Resistive Switching Test Circuit and Waveform

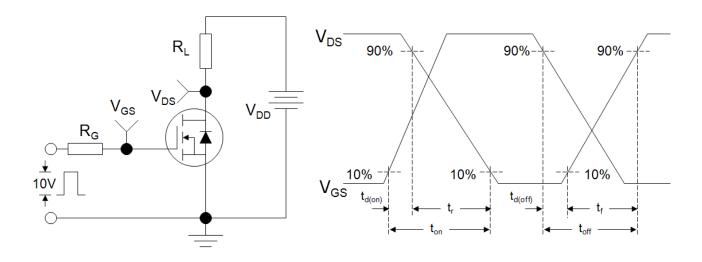
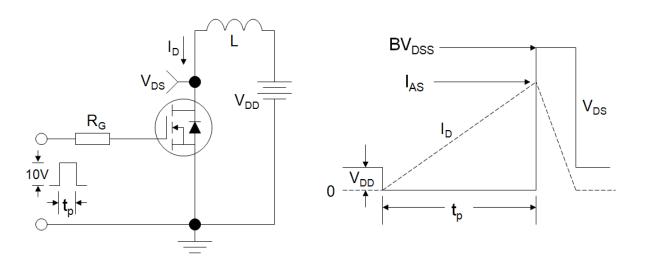


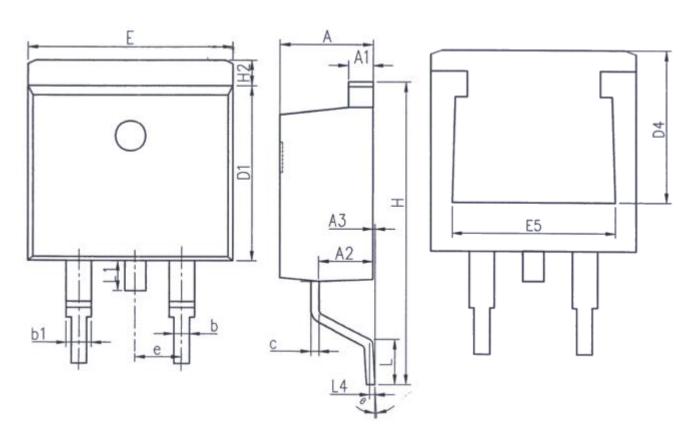
Figure C: Unclamped Inductive Switching Test Circuit and Waveform



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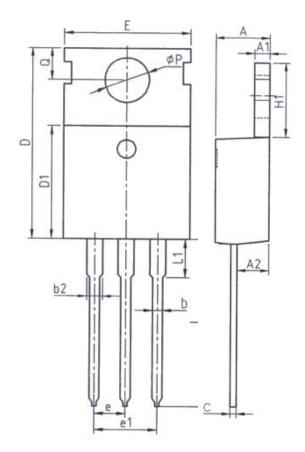


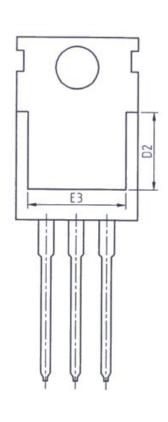
Unit: mm			
Symbol	Symbol Min.		
Α	4. 37	4. 77	
A 1	1. 22	1. 42	
A2	2. 49	2. 89	
A3	0. 00	0. 25	
b	0. 70	0.96	
b1	1. 17	1. 47	
С	0. 30	0. 53	
D1	8. 50	8. 90	
D4	6. 60	_	

Unit: mm			
Symbol	Min.	Max.	
E	9.86	10.36	
E 5	7. 06	-	
е	2. 54BSC		
Н	14. 70	15. 50	
H2	1. 07	1. 47	
L	2.00	2. 60	
L1	1. 40	1. 70	
L4	0. 25BSC		
θ	0°	9°	



TO-220





Unit: mm			
Symbol	Min.	Max.	
Α	4. 37	4. 77	
A1	1. 25	1. 45	
A2	2. 20	2. 60	
b	0. 70	0. 95	
b2	1. 17	1. 47	
С	0. 40	0. 65	
D	15. 10	16. 10	
D1	8. 80	9. 40	
D2	5. 50	_	

Unit: mm			
Symbol	Min. Max.		
E	9. 70	10. 30	
E3	7. 00	_	
е	2. 54BSC		
e1	5. 08BSC		
H1	6. 25	6. 85	
L	12. 75 13. 8		
L1	- 3.40		
Р	3. 40 3. 80		
Q	2. 60 3. 00		



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